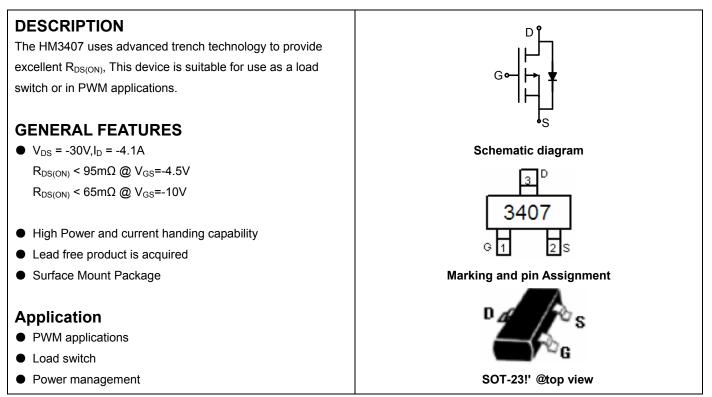
## P-Channel Enhancement Mode Power MOSFET



#### Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3407	HM3407	SOT-23ËHŠ	Ø180mm	8 mm	3000 units

#### Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	Ι <sub>D</sub>	-4.1	A
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	-20	A
Maximum Power Dissipation	PD	1.4	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	°C

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	R <sub>θJA</sub>	90	°C/W
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#### Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250µA	-30	-33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =-24V, $V_{GS}$ =0V	-	-	-1	μA

Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250µA	-1	-1.5	-3	V
Drain-Source On-State Resistance		V <sub>GS</sub> =-10V, I <sub>D</sub> =-4.1A	-	55	65	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A	-	75	95	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =-5V,I <sub>D</sub> =-4.1A	5.5	-	-	S
Dynamic Characteristics (Note4)		·				
Input Capacitance	C <sub>lss</sub>	(-45)()(-0)(	-	700	-	PF
Output Capacitance	C <sub>oss</sub>	- V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V, - F=1.0MHz	-	120	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	75	-	PF
Switching Characteristics (Note 4)		·				
Turn-on Delay Time	t <sub>d(on)</sub>		-	9	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =-15V,R <sub>L</sub> =3.6Ω	-	5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10V, $R_{GEN}$ =3 $\Omega$	-	28	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	13.5	-	nS
Total Gate Charge	Qg		-	14	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-15V,I <sub>D</sub> =-4A,V <sub>GS</sub> =-10V	-	3.1	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	3.	-	nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-1A	-	-	-1.2	V

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

**2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.

**3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

4. Guaranteed by design, not subject to production

## **TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

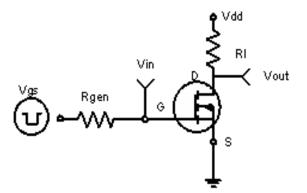


Figure 1:Switching Test Circuit

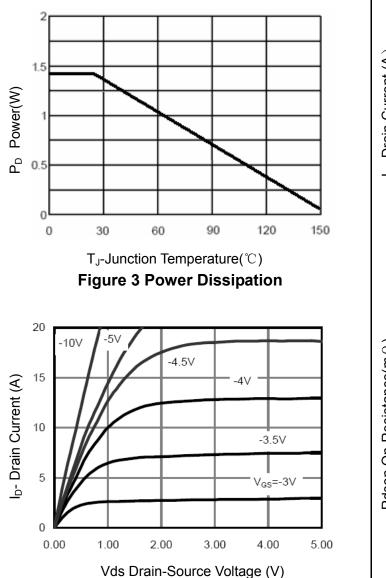
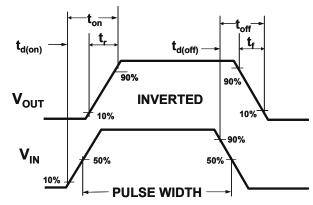
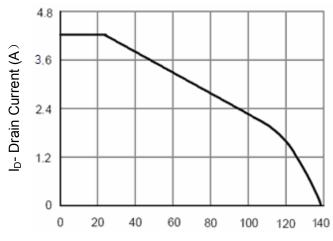


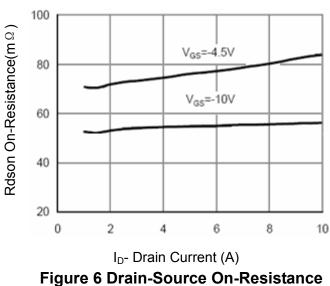
Figure 5 Output CHARACTERISTICS

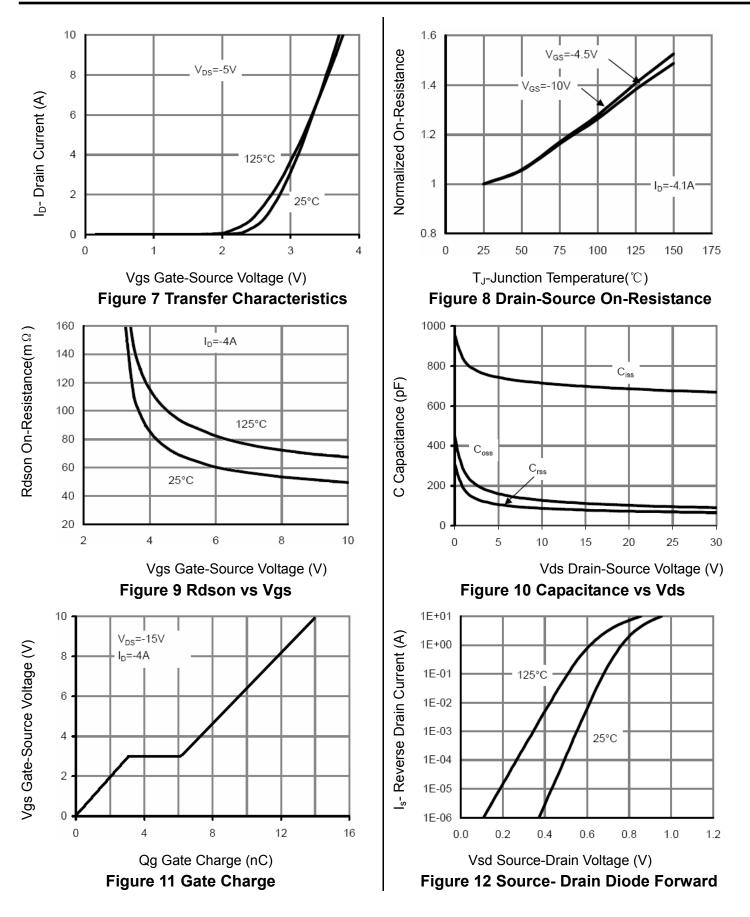






T<sub>J</sub>-Junction Temperature(℃) Figure 4 Drain Current





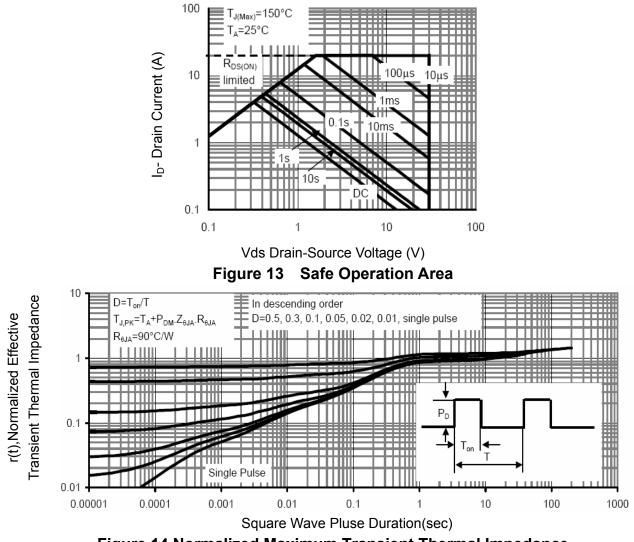
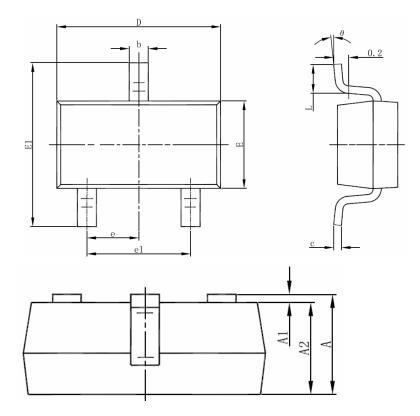


Figure 14 Normalized Maximum Transient Thermal Impedance

# SOT-23-3L PACKAGE INFORMATION



Symbol	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
с	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950	(BSC)	0.037(	BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

## NOTES

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

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